

**Amendments to the Specification:**

Please replace the paragraph beginning on page 9, line 24, with the following amended paragraph:

From FIGS. 1-3, it is clear that the transfer heads 14 may be moved along a circle 20 indicated by a dash-dotted line, where each transfer head 14 may be taken in a chip pick-up position near the first plane 2, and in a chip bonding position near the second plane 4 along the circle 20, transferring each chip either in a clockwise or a counter-clockwise direction from a wafer to a lead frame. In the arrangements of FIGS. 1-3, with a proper choice of angles  $\alpha$  ~~en~~ and  $\beta$  and the radius of the circle 20, and a corresponding arrangement of transfer heads 14 along the circle 20, an optimum configuration in a limited space can be obtained.